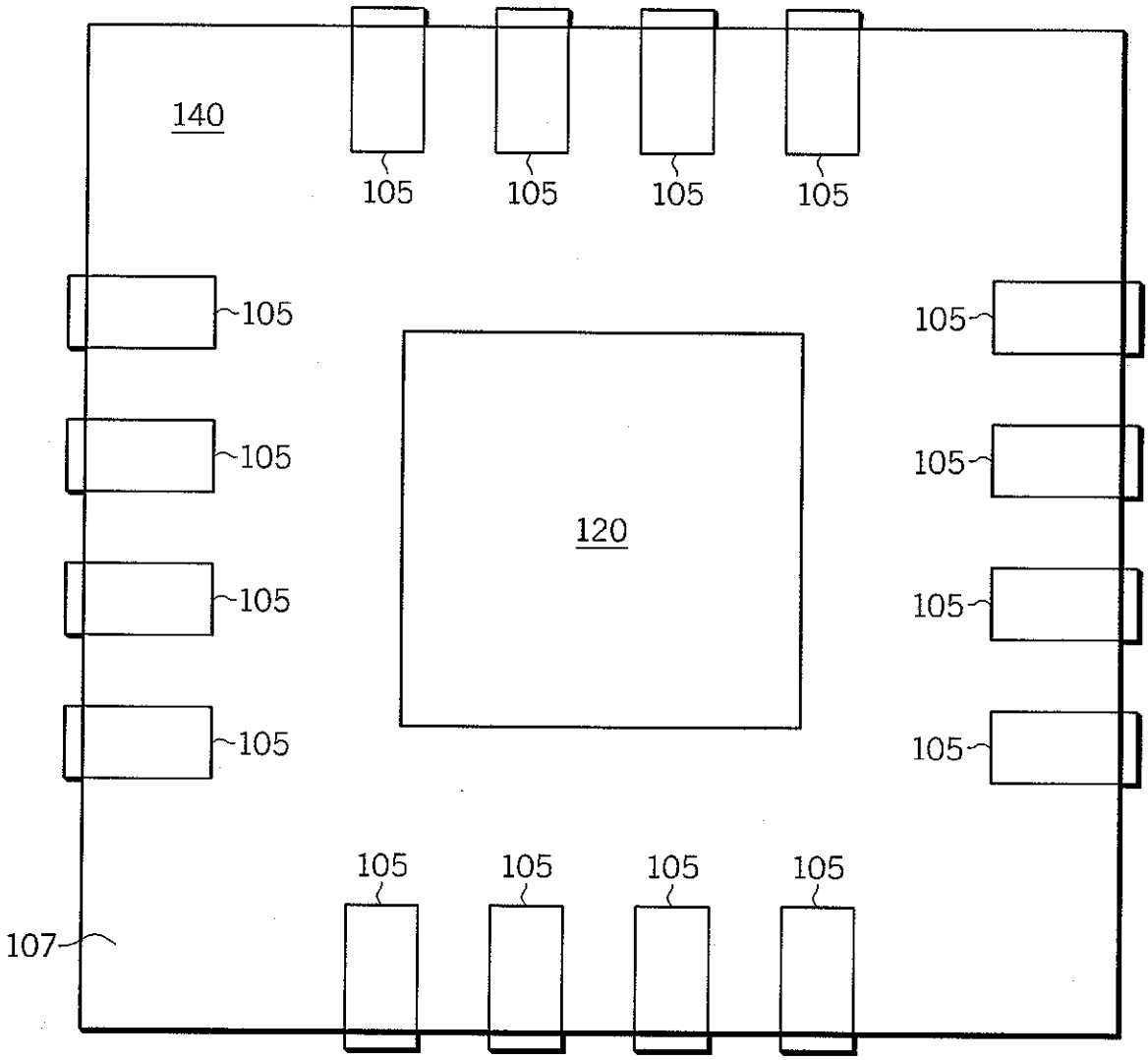


FIG. 1 100
-PRIOR ART-

FIG. 2
-PRIOR ART-

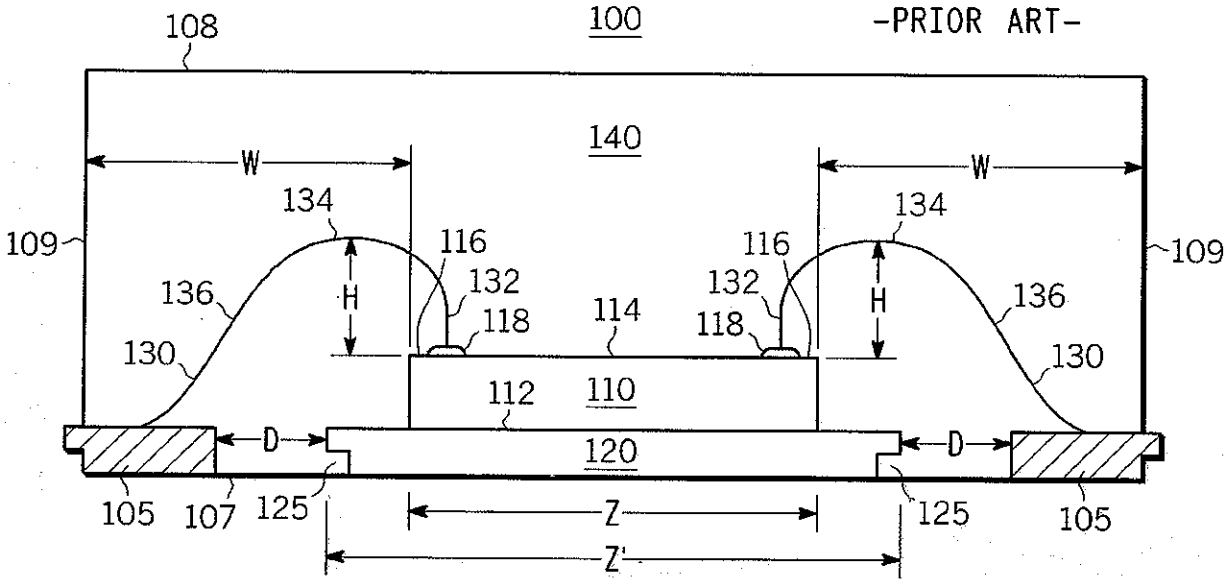


FIG. 3

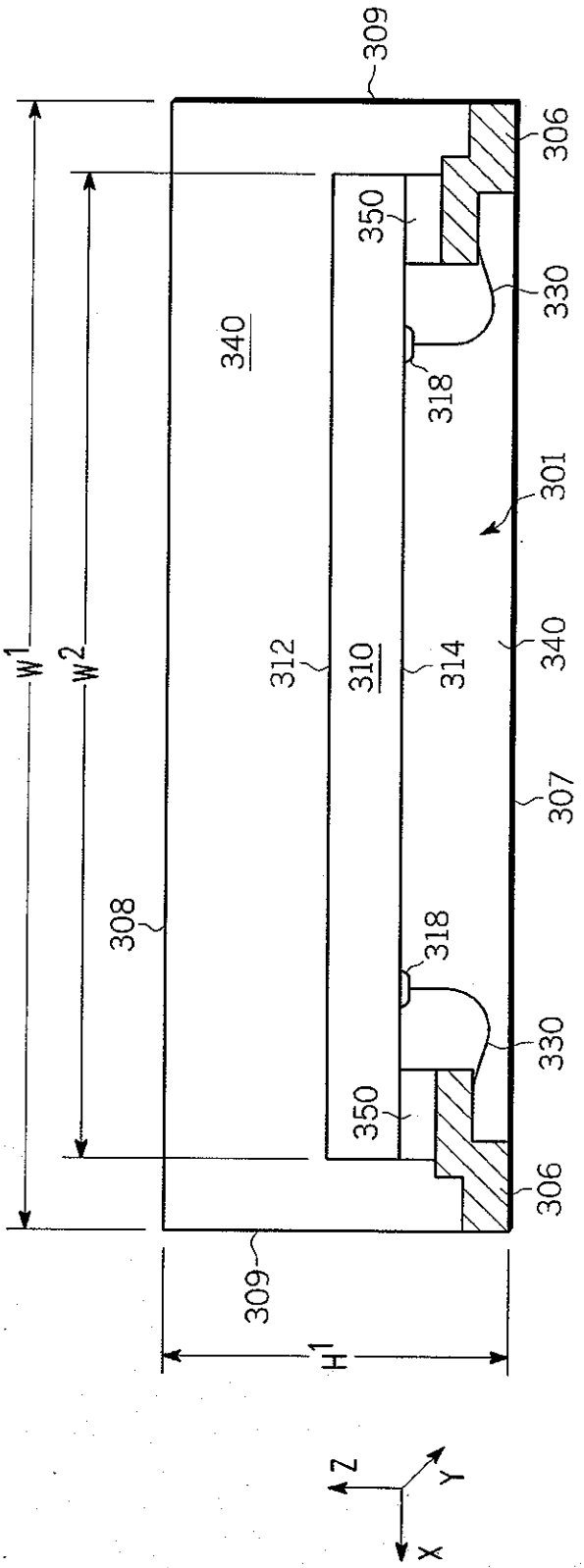
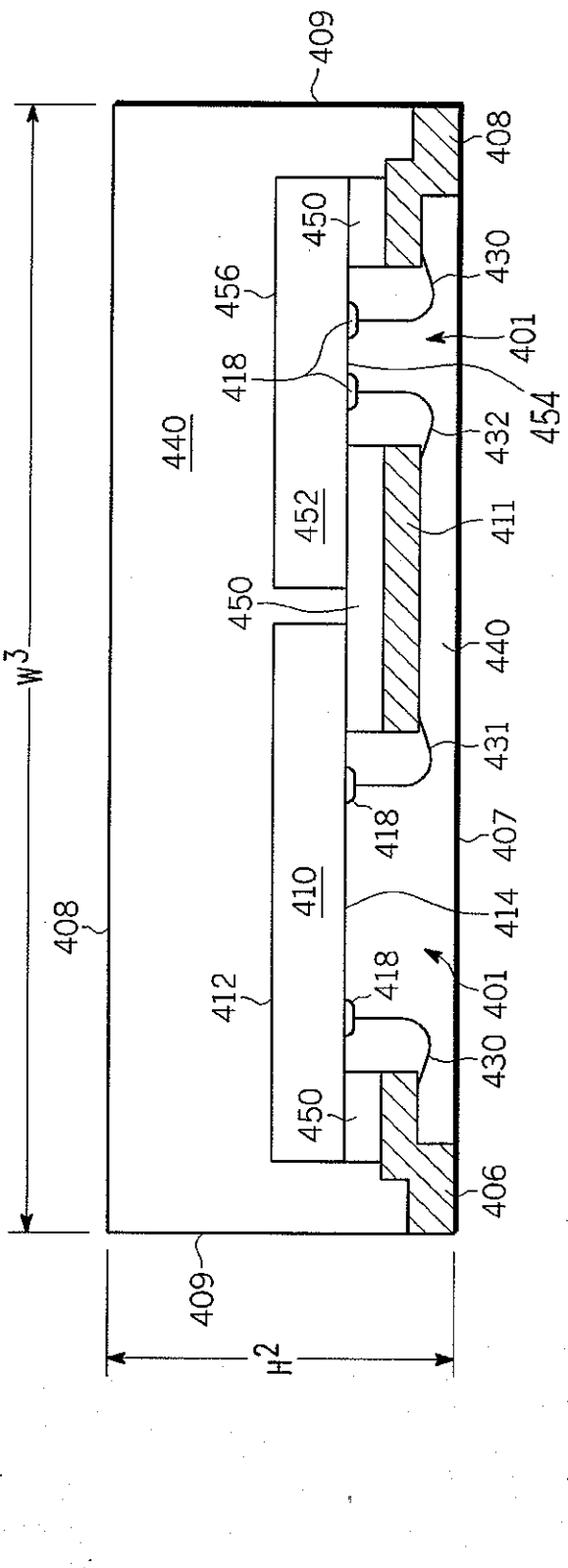

300
309
306
350
330
340
318
301
312
310
314
340
307
308
318
330
350
306
309
W^1
W^2
H^1
Z
Y
X

FIG. 5


400
409
408
450
430
456
401
418
454
440
432
452
411
450
440
431
418
407
410
414
412
418
401
430
450
406
409
408
W^3
H^2

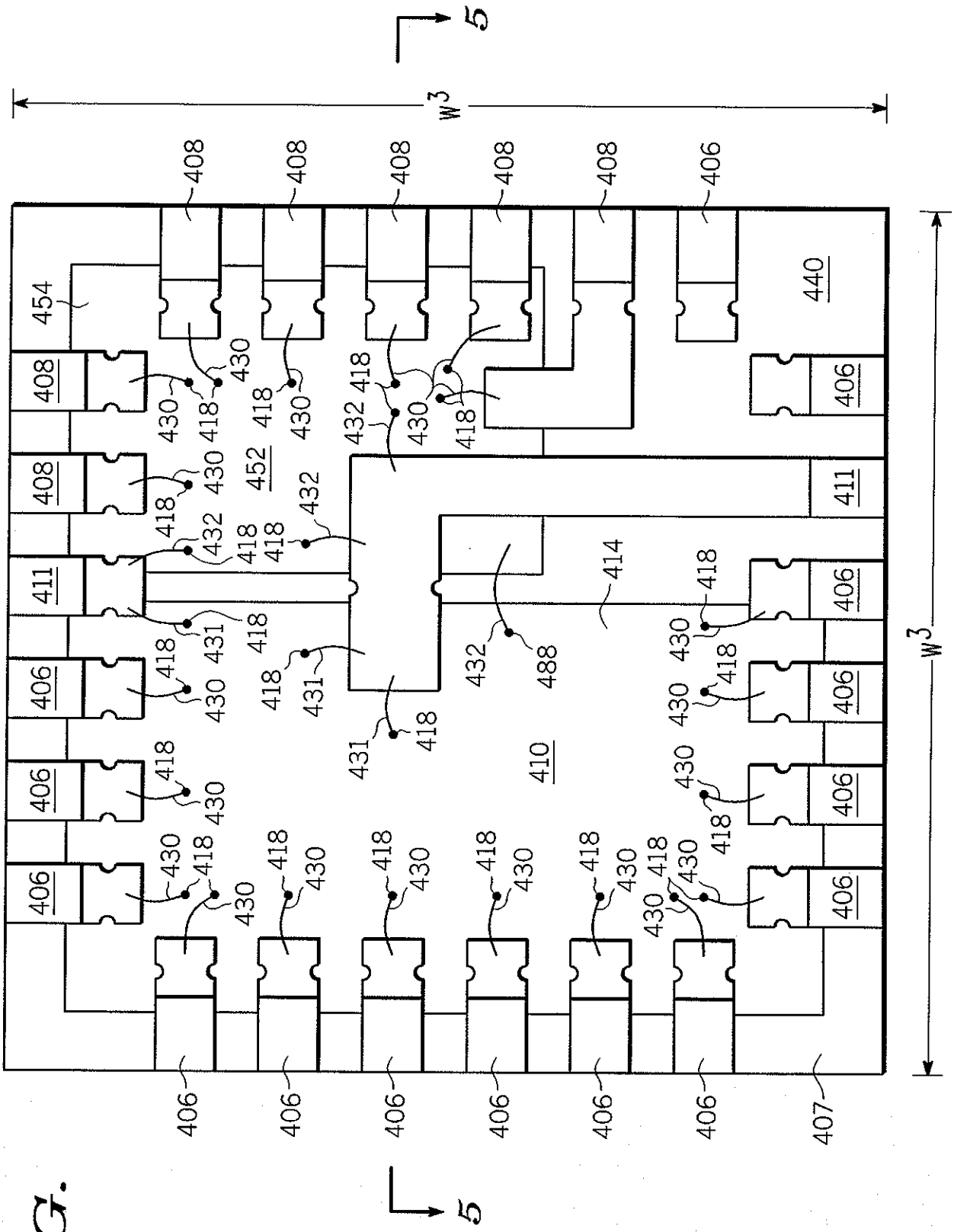

5
W3
408
406
454
440
452
411
414
410
418
430
432
431
488
W3
5
400
407

FIG. 4

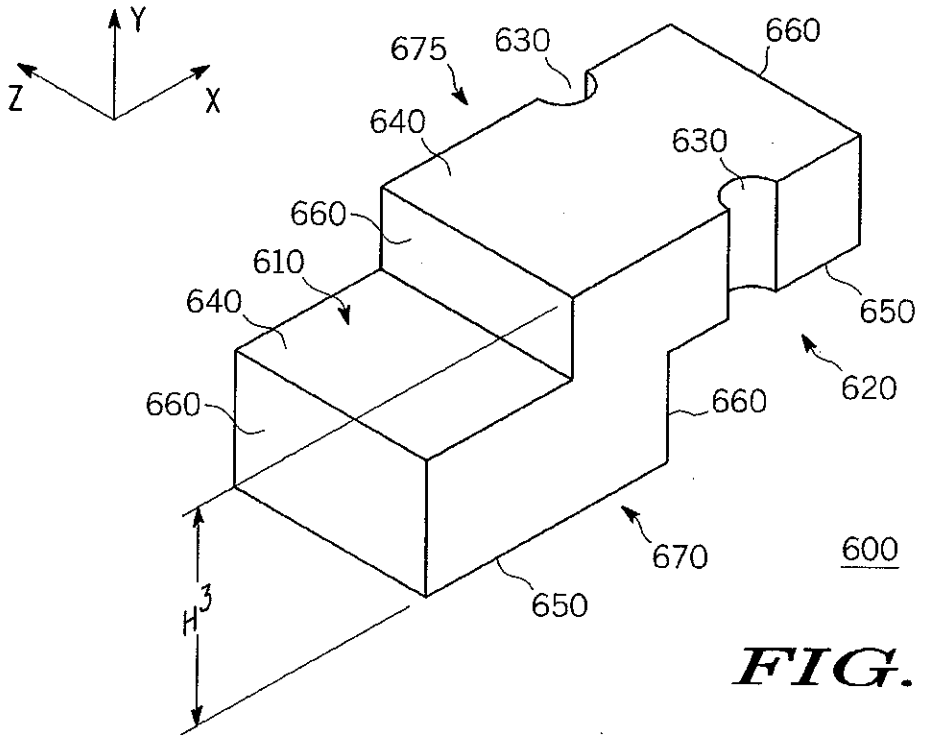
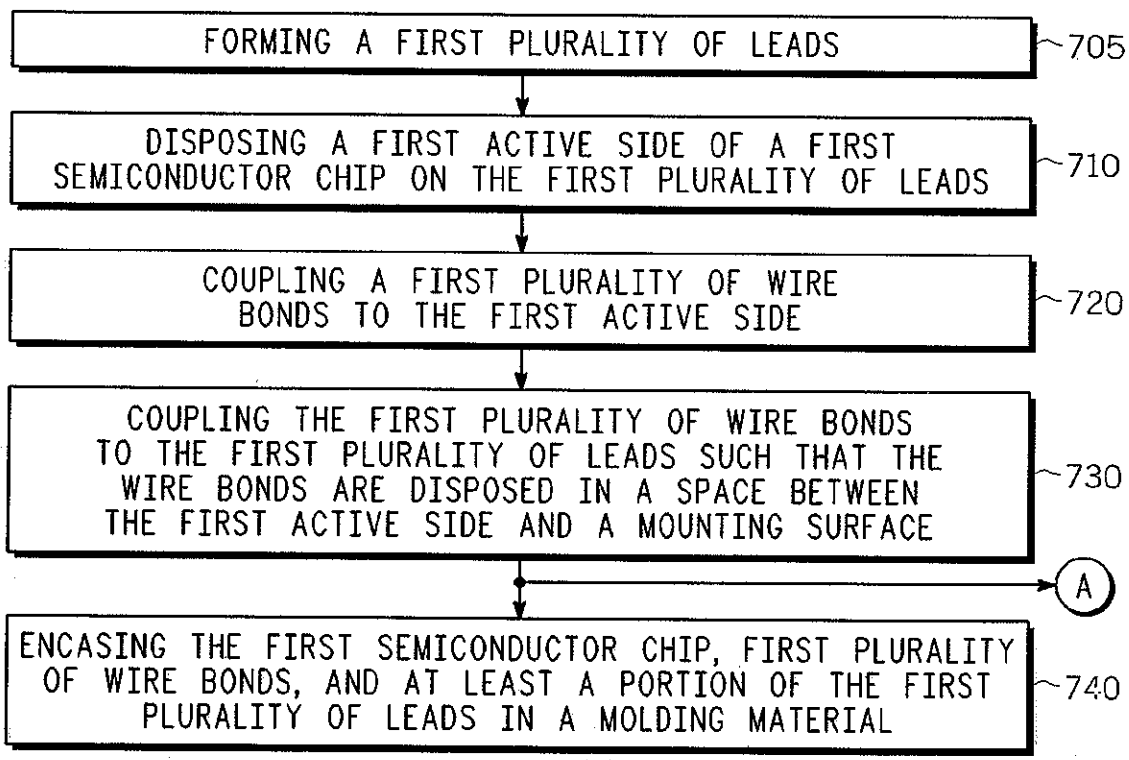

Y
Z
X
675
630
660
640
630
660
610
640
650
620
660
660
670
600
650
H3

FIG. 6

FIG. 7A


FORMING A FIRST PLURALITY OF LEADS
705
DISPOSING A FIRST ACTIVE SIDE OF A FIRST SEMICONDUCTOR CHIP ON THE FIRST PLURALITY OF LEADS
710
COUPLING A FIRST PLURALITY OF WIRE BONDS TO THE FIRST ACTIVE SIDE
720
COUPLING THE FIRST PLURALITY OF WIRE BONDS TO THE FIRST PLURALITY OF LEADS SUCH THAT THE WIRE BONDS ARE DISPOSED IN A SPACE BETWEEN THE FIRST ACTIVE SIDE AND A MOUNTING SURFACE
730
A
ENCASING THE FIRST SEMICONDUCTOR CHIP, FIRST PLURALITY OF WIRE BONDS, AND AT LEAST A PORTION OF THE FIRST PLURALITY OF LEADS IN A MOLDING MATERIAL
740

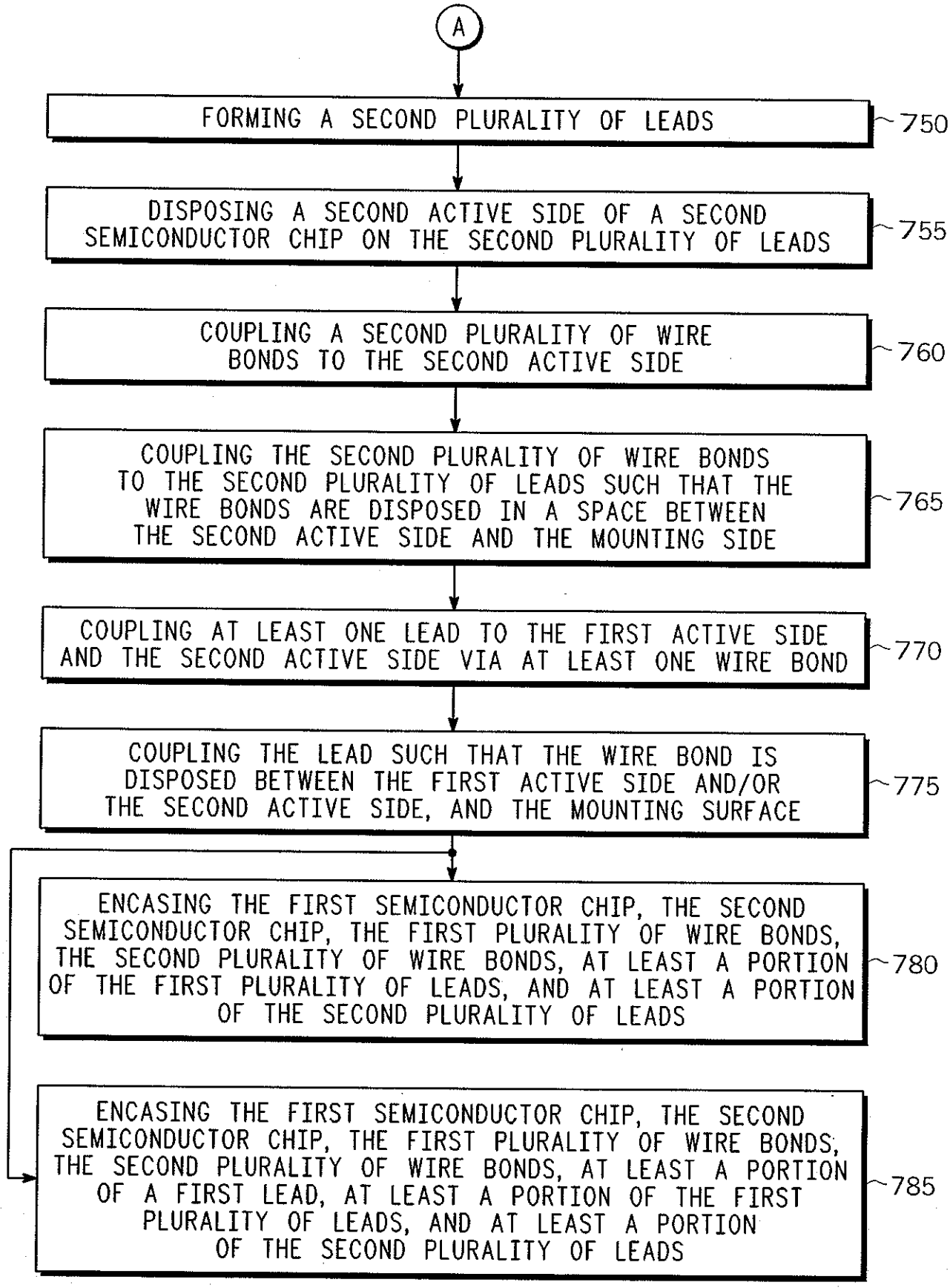

A
FORMING A SECOND PLURALITY OF LEADS
750
DISPOSING A SECOND ACTIVE SIDE OF A SECOND SEMICONDUCTOR CHIP ON THE SECOND PLURALITY OF LEADS
755
COUPLING A SECOND PLURALITY OF WIRE BONDS TO THE SECOND ACTIVE SIDE
760
COUPLING THE SECOND PLURALITY OF WIRE BONDS TO THE SECOND PLURALITY OF LEADS SUCH THAT THE WIRE BONDS ARE DISPOSED IN A SPACE BETWEEN THE SECOND ACTIVE SIDE AND THE MOUNTING SIDE
765
COUPLING AT LEAST ONE LEAD TO THE FIRST ACTIVE SIDE AND THE SECOND ACTIVE SIDE VIA AT LEAST ONE WIRE BOND
770
COUPLING THE LEAD SUCH THAT THE WIRE BOND IS DISPOSED BETWEEN THE FIRST ACTIVE SIDE AND/OR THE SECOND ACTIVE SIDE, AND THE MOUNTING SURFACE
775
ENCASING THE FIRST SEMICONDUCTOR CHIP, THE SECOND SEMICONDUCTOR CHIP, THE FIRST PLURALITY OF WIRE BONDS, THE SECOND PLURALITY OF WIRE BONDS, AT LEAST A PORTION OF THE FIRST PLURALITY OF LEADS, AND AT LEAST A PORTION OF THE SECOND PLURALITY OF LEADS
780
ENCASING THE FIRST SEMICONDUCTOR CHIP, THE SECOND SEMICONDUCTOR CHIP, THE FIRST PLURALITY OF WIRE BONDS, THE SECOND PLURALITY OF WIRE BONDS, AT LEAST A PORTION OF A FIRST LEAD, AT LEAST A PORTION OF THE FIRST PLURALITY OF LEADS, AND AT LEAST A PORTION OF THE SECOND PLURALITY OF LEADS
785

FIG. 7B